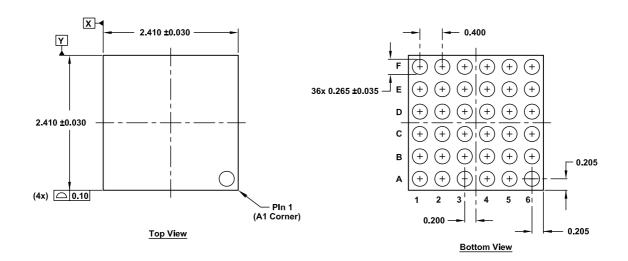
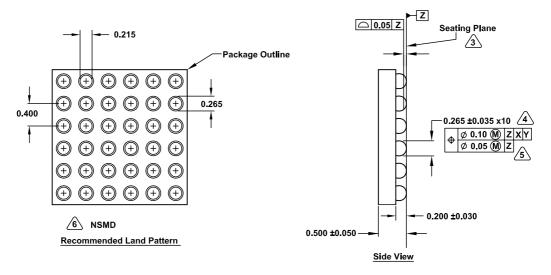
Plastic Packages for Integrated Circuits

Package Outline Drawing

W6x6.36D 36 Ball Wafer Level Chip Scale Package (WLCSP 0.4mm Pitch) Rev 1, 10/19





NOTES:

- 1. All dimensions are in millimeters.
- 2. Dimensions and tolerances per ASME Y14.5-1994.
- Primary datum Z and seating plane are defined by the spherical crowns of the bump.
- \overline{A} Dimension is measured at the maximum bump diameter parallel to primary datum \overline{Z} .
- 5. Bump position designation per JESD 95-1, SPP-010.
- NSMD refers to non-solder mask defined pad design per TB451.